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|  | ITk Pixel – Outer Endcaps Loaded Local Supports  ATLAS ITk-Pixel Project | | | |
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| Local Supports Loading  for the ITk Pixel Outer Endcaps  Provided for the ITk Pixel Outer System Loaded Local Supports Preliminary Readiness Review  28 February – xxx 2024  This document describes the procedures and equipment for the loading of modules and on-detector services in the ITk Pixel Outer Endcaps. It also describes the validation of these procedures and equipment. | | | |
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Table of Contents

[1 Introduction 6](#_Toc160184131)

[2 Lab infrastructure 6](#_Toc160184132)

[2.1 Clean Room 6](#_Toc160184133)

[2.2 Vacuum 6](#_Toc160184134)

[2.3 Dry air 6](#_Toc160184135)

[2.4 Gantry 6](#_Toc160184136)

[2.5 Microscope 6](#_Toc160184137)

[2.6 Z height measurements 6](#_Toc160184138)

[2.7 Glue deposition and mixing 6](#_Toc160184139)

[2.8 Auxiliary equipment 6](#_Toc160184140)

[2.9 Environmental monitoring 6](#_Toc160184141)

[3 Storage 6](#_Toc160184142)

[3.1 Quad Modules 6](#_Toc160184143)

[3.2 Unloaded Half Ring 6](#_Toc160184144)

[3.3 Power Pig Tail and data PP0 6](#_Toc160184145)

[3.4 SE4445 glue and Glass spheres 6](#_Toc160184146)

[3.5 Loaded Half Ring 6](#_Toc160184147)

[4 Handling and protection 6](#_Toc160184148)

[4.1 Quad Modules 6](#_Toc160184149)

[4.2 Unloaded Half Ring 6](#_Toc160184150)

[4.3 Power Pig Tail 6](#_Toc160184151)

[4.4 Data PP0 6](#_Toc160184152)

[4.5 SE4445 glue and Glass spheres 6](#_Toc160184153)

[4.6 Glued Module 6](#_Toc160184154)

[4.7 Loaded Half Ring 6](#_Toc160184155)

[5 Reception tests 6](#_Toc160184156)

[5.1 Quad Modules 6](#_Toc160184157)

[5.1.1 Environmental box 6](#_Toc160184158)

[5.1.2 Cooling system 7](#_Toc160184159)

[5.1.3 DCS 7](#_Toc160184160)

[5.1.4 Interlock hardware and matrix 7](#_Toc160184161)

[5.2 Bus Tape on Half Ring 7](#_Toc160184162)

[5.2.1 Setup 7](#_Toc160184163)

[5.2.2 Test procedure 7](#_Toc160184164)

[6 Module Loading 7](#_Toc160184165)

[6.1 Gantry XYcalibration with optical calibration plate 7](#_Toc160184166)

[6.2 Parking tool planarity adjustment 7](#_Toc160184167)

[6.3 Pick-up head planarity adjustment 7](#_Toc160184168)

[6.4 Half Ring positioning on Gantry 7](#_Toc160184169)

[6.5 Half Ring reference system 7](#_Toc160184170)

[6.6 Half Ring z map 7](#_Toc160184171)

[6.7 Quad Module tab cutting 7](#_Toc160184172)

[6.8 Quad Module parking on vacuum tool 7](#_Toc160184173)

[6.9 Quad Module XYZ metrology 7](#_Toc160184174)

[6.10 Quad Module pick-up 7](#_Toc160184175)

[6.11 Quad Module placement and position tolerance 7](#_Toc160184176)

[6.12 Glue curing 7](#_Toc160184177)

[6.13 Second Side Loading 7](#_Toc160184178)

[6.14 Loaded Half Ring XYZ metrology 7](#_Toc160184179)

[7 Power pig tail soldering 7](#_Toc160184180)

[7.1 Soldering tool calibration 7](#_Toc160184181)

[7.2 Soldering tool and setup 7](#_Toc160184182)

[7.3 Soldering preparation 7](#_Toc160184183)

[7.4 Soldering procedure 7](#_Toc160184184)

[8 Reworking 7](#_Toc160184185)

[8.1 Tools 7](#_Toc160184186)

[8.2 Procedure 7](#_Toc160184187)

[9 QC setup and tests 8](#_Toc160184188)

[9.1 Environmental box 8](#_Toc160184189)

[9.2 Cooling system 8](#_Toc160184190)

[9.3 DCS 8](#_Toc160184191)

[9.4 Interlock hardware and matrix 8](#_Toc160184192)

[9.5 DAQ 8](#_Toc160184193)

[9.6 Thermal cycle 8](#_Toc160184194)

[9.7 Electrical tests 8](#_Toc160184195)

[9.8 Non-electrical tests 8](#_Toc160184196)

[10 PDB 8](#_Toc160184197)

[10.1 Electrical tests 8](#_Toc160184198)

[10.2 Metrology 8](#_Toc160184199)

[10.3 Visual Inspection 8](#_Toc160184200)

[11 Storage 8](#_Toc160184201)

[12 Transport 8](#_Toc160184202)

# Introduction

# Lab infrastructure

Ben Smart

## Clean Room

## Vacuum

## Dry air

## Gantry

## Microscope

## Z height measurements

## Glue deposition and mixing

## Auxiliary equipment

## Environmental monitoring

# Storage

Gabriele Chiodini

## Quad Modules

## Unloaded Half Ring

## Power Pig Tail and data PP0

## SE4445 glue and Glass spheres

## Loaded Half Ring

# Handling and protection

Gabriele Chiodini

## Quad Modules

## Unloaded Half Ring

## Power Pig Tail

## Data PP0

## SE4445 glue and Glass spheres

## Glued Module

## Loaded Half Ring

# Reception tests

Ben Smart

## Quad Modules

### Environmental box

### Cooling system

### DCS

### Interlock hardware and matrix

## Bus Tape on Half Ring

### Setup

### Test procedure

# Module Loading

Ben Smart

## Gantry XYcalibration with optical calibration plate

## Parking tool planarity adjustment

## Pick-up head planarity adjustment

## Half Ring positioning on Gantry

## Half Ring reference system

## Half Ring z map

## Quad Module tab cutting

## Quad Module parking on vacuum tool

## Quad Module XYZ metrology

## Quad Module pick-up

## Quad Module placement and position tolerance

## Glue curing

## Second Side Loading

## Loaded Half Ring XYZ metrology

# Power pig tail soldering

Genova

## Soldering tool calibration

## Soldering tool and setup

## Soldering preparation

## Soldering procedure

# Reworking

Ben Smart

## Tools

## Procedure

# QC setup and tests

Daniel Hynds

## Environmental box

## Cooling system

## DCS

## Interlock hardware and matrix

## DAQ

Genova

## Thermal cycle

Stefano

## Electrical tests

## Non-electrical tests

# PDB

Juliette Martin

## Electrical tests

## Metrology

## Visual Inspection

# Storage

Gabriele Chiodini

# Transport

Daniel Hynds